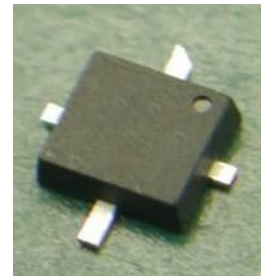


FEATURES

- High Output Power: P1dB=35.5dBm(typ.)
- High Gain: G1dB=11.5dB(typ.)
- Low Cost Plastic(SMT) Package
- Tape and Reel Available

DESCRIPTION

The FLU35ZME1 is a GaAs FET designed for base station and CPE application up to a 4.0GHz frequency range. This is a new product series using a plastic surface mount package that has been optimized for high volume cost driven applications. SUMITOMO's stringent Quality Assurance Program assures the highest reliability and consistent performance.



ABSOLUTE MAXIMUM RATINGS (Case Temperature Tc=25deg.C)

Item	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	15	V
Gate-Source Voltage	V _{GS}	-5	V
Total Power Dissipation	P _T	20.8	W
Storage Temperature	T _{stg}	-55 to +150	deg.C
Channel Temperature	T _{ch}	150	deg.C

RECOMMENDED OPERATING CONDITION(Case Temperature Tc=25deg.C)

Item	Symbol	Condition	Unit
DC Input Voltage	V _{DS}	≤ 10	V
Forward Gate Current	I _{GF}	≤ 19.4	mA
Reverse Gate Current	I _{GR}	≥ -2.0	mA
Gate Resistance	R _g	100	ohm
Channel Temperature	T _{ch}	≤ 145	deg.C

ELECTRICAL CHARACTERISTICS (Case Temperature Tc=25deg.C)

Item	Symbol	Test Conditions	Limit			Unit
			Min.	Typ.	Max.	
Drain Current	I _{DSS}	V _{DS} =5V, V _{GS} =0V	-	1200	1800	mA
Trans Conductance	g _m	V _{DS} =5V, I _{DS} =800mA	-	600	-	mS
Pinch-off Voltage	V _p	V _{DS} =5V, I _{DS} =60mA	-1.0	-2.0	-3.5	V
Gate-Source Breakdown Voltage	V _{GSO}	I _{GS} =-60μA	-5	-	-	V
Output Power at 1dB G.C.P.	P _{1dB}	V _{DS} =10V f=2.0GHz	34.5	35.5	-	dBm
Power Gain at 1dB G.C.P.	G _{1dB}	I _{DS} =0.6I _{DSS} (Typ.)	10.5	11.5	-	dB
Thermal Resistance	R _{th}	Channel to Case	-	5	6	deg.C/W

Note1: Product supplied to this specification are 100% DC performance tested.

Note2: The RF parameters are measured on a lot basis by sample testing 10 pcs/lot.

Acceptance Criteria:(accept/reject)=(0/1). Any lot failure shall be 100% retested.

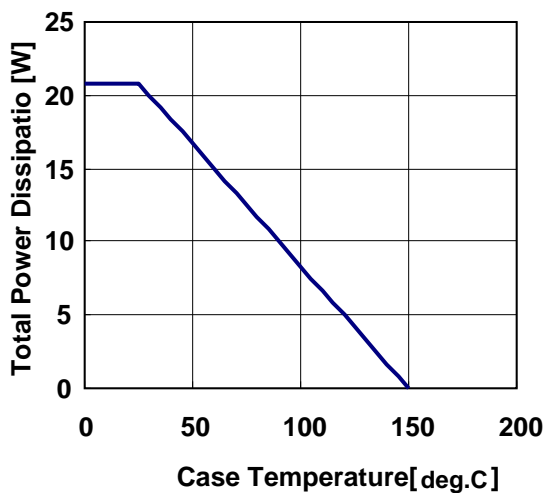
G.C.P.:Gain Compression Point

ESD	Class III	2000 V min.
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RoHS COMPLIANCE	Yes
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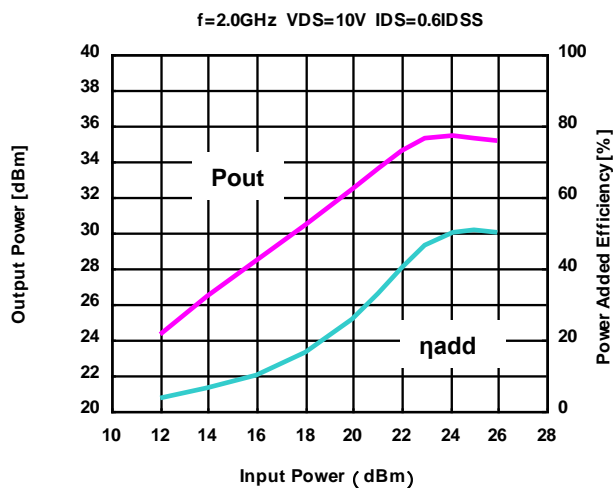
Note : Based on EIAJ ED-4701 C-111A (C=100pF,R=1.5kohm)

POWER DERATING CURVE



TUNING CONDITION : f=2.0GHz, FINE TUNED

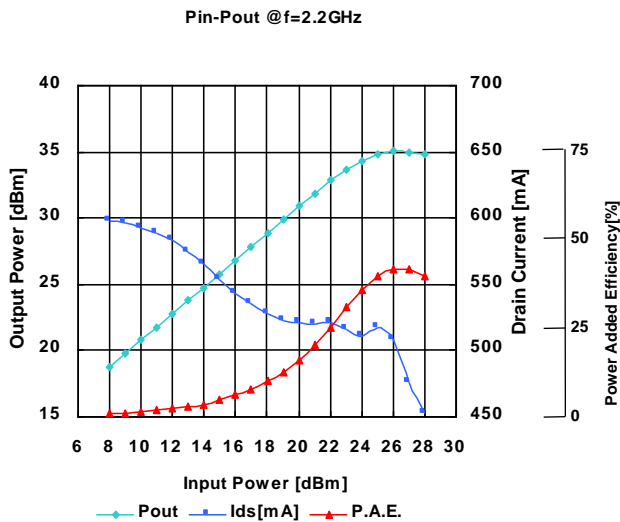
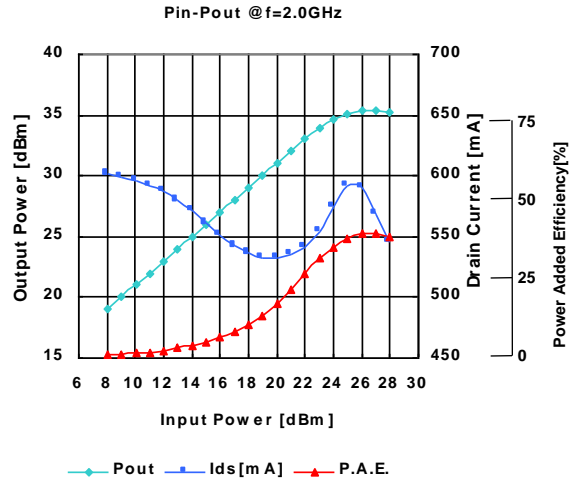
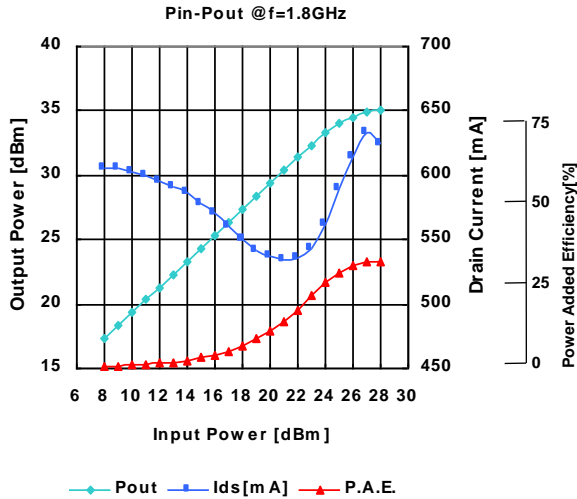
OUTPUT POWER , POWER ADDED EFFICIENCY vs. INPUT POWER



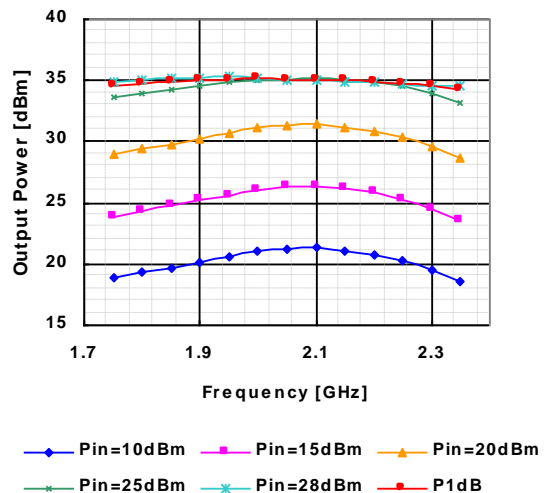
TUNING CONDITION : WIDE BAND TUNED

OUTPUT POWER , DRAIN CURRENT vs. INPUT POWER

@ VDS=10V IDS(DC)=0.6IDSS

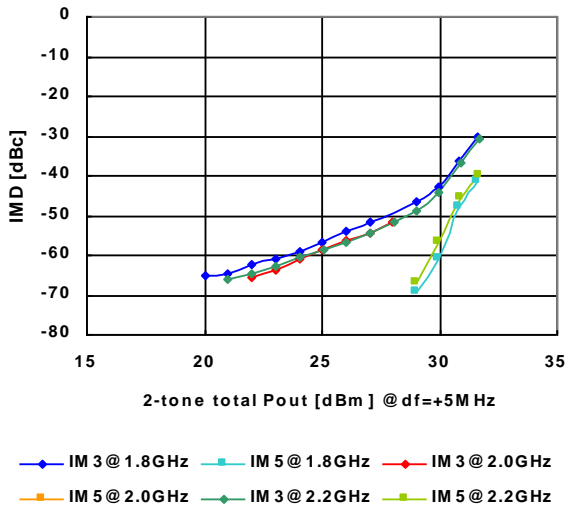


OUTPUT POWER vs. FREQUENCY

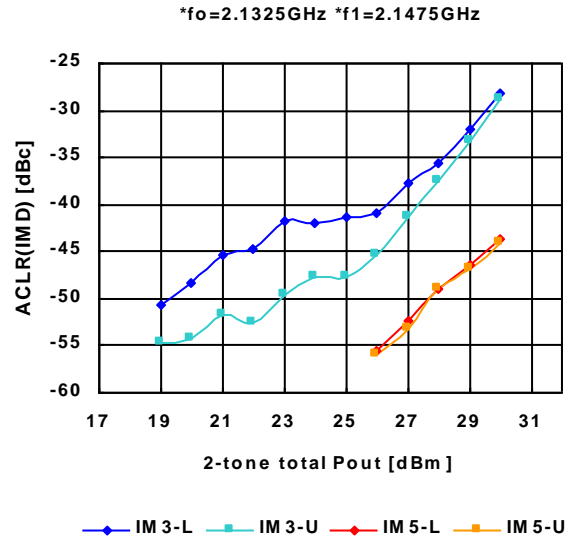


@ VDS=10V IDS(DC)=0.6IDSS

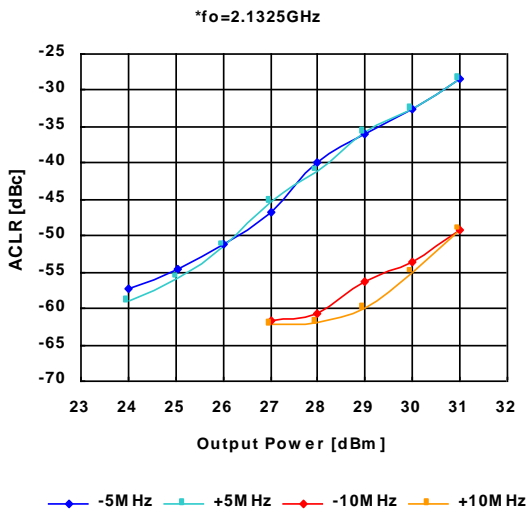
IMD vs OUTPUT POWER(2-tone)



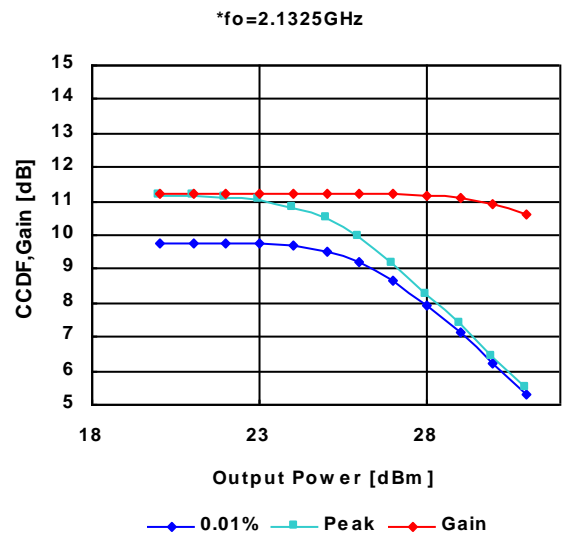
W-CDMA 2-CARRIER IMD(ACLR)



W-CDMA SINGLE CARRIER ACLR

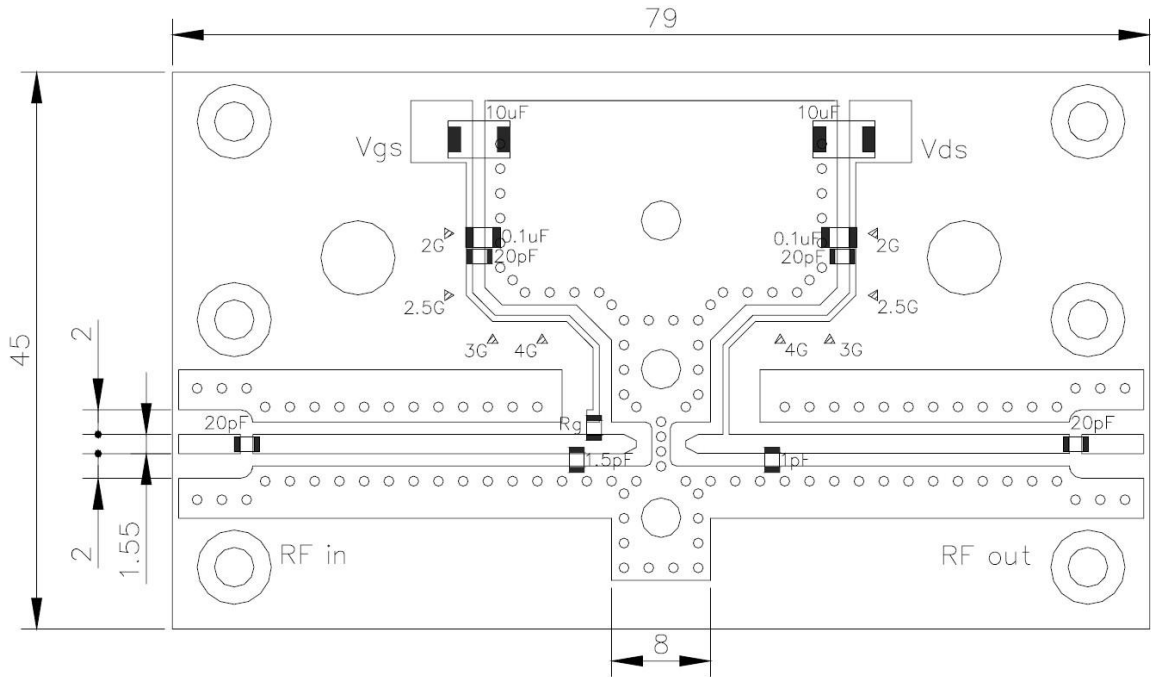


W-CDMA SINGLE CARRIER CCDF AND GAIN



Note : *All signal are W-CDMA modulation at 3GPP3.4.12-00 BS-1 64ch non clipping.

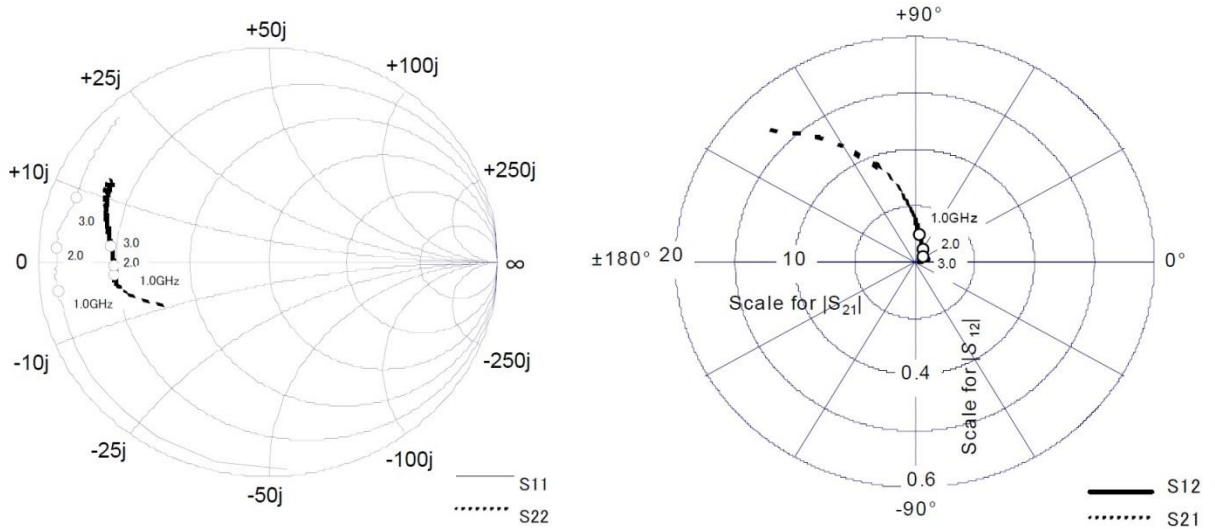
■ Recommended Bias Circuit and Internal Block Diagram



<Board information>
 $\epsilon_r=3.5$, $t=0.8$

* Board was tuned for wide band performance that is presented in page 4 and 5.

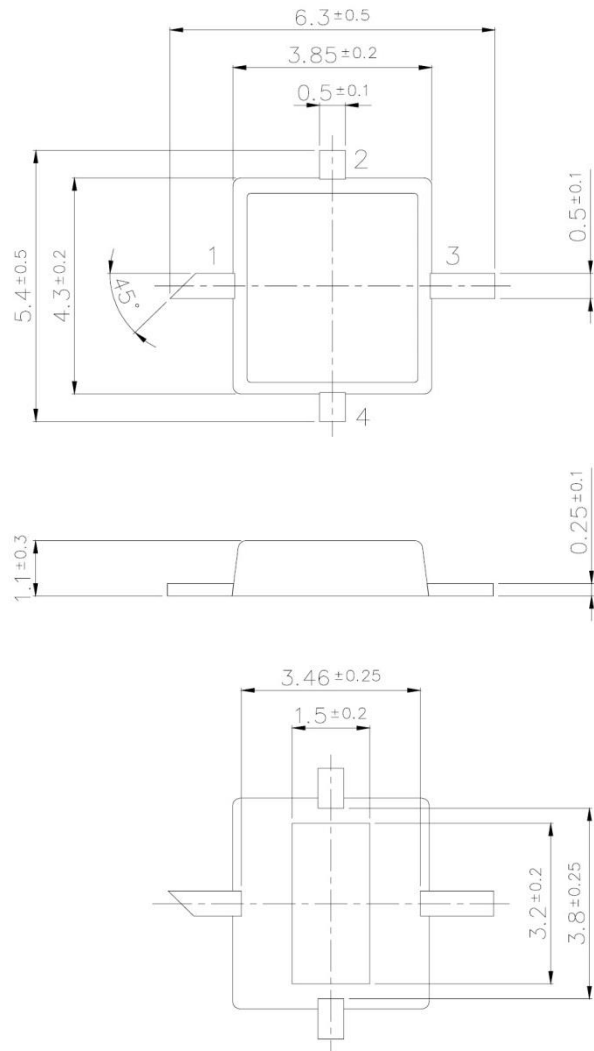
■ S-PARAMETER



VDS=10V , IDS=0.6IDSS(TYP.)

Freq [GHz]	S11		S21		S12		S22	
	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
0.5	0.92	-157.14	4.75	94.86	0.03	14.31	0.67	-172.46
1	0.92	-171.65	2.45	81.26	0.03	9.28	0.67	-175.16
1.5	0.92	-178.09	1.69	70.63	0.03	7.87	0.66	-176.48
2	0.92	175.59	1.32	61.24	0.03	11.56	0.67	-178.45
2.5	0.92	168.62	1.08	50.14	0.03	10.17	0.67	178.10
3	0.89	159.87	0.90	39.03	0.03	16.31	0.69	173.63
3.5	0.90	150.98	0.76	27.30	0.03	13.26	0.71	167.99
4	0.91	143.89	0.64	16.94	0.03	14.12	0.74	162.05
4.5	0.93	137.22	0.54	6.74	0.03	7.95	0.77	156.46
5	0.93	133.89	0.45	-1.01	0.03	9.18	0.78	151.30

■ Package Outline



- 1 : Gate
 - 2 : Source
 - 3 : Drain
 - 4 : Source
- Unit : mm

For further information please contact:

<http://global-sei.com/Electro-optic/about/office.html>

CAUTION

This product contains **gallium arsenide (GaAs)** which can be hazardous to the human body and the environment.

For safety, observe the following procedures:

- Do not put these products into the mouth.
- Do not alter the form of this product into a gas, powder, or liquid through burning, crushing, or chemical processing as these by-products are dangerous to the human body if inhaled, ingested, or allowed.
- Observe government laws and company regulations when discarding this product.
This product must be discarded in accordance with methods specified by applicable hazardous waste procedures.